



SOLID STATE DEVICES, INC

14849 Firestone Boulevard · La Mirada, CA 90638  
 Phone: (714) 670-SSDI (7734) · Fax: (714) 522-7424

**SFFC50**

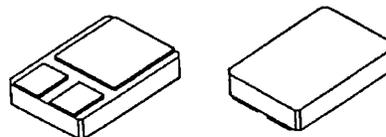
**11 AMP  
 600 VOLTS  
 0.6 Ω  
 N-CHANNEL  
 POWER MOSFET**

**Designer's Data Sheet**

**FEATURES:**

- Rugged construction with poly silicon gate
- Low RDS(on) and high transconductance
- Excellent high temperature stability
- Very fast switching speed
- Fast recovery and superior dv/dt performance
- Increased reverse energy capability
- Low input and transfer capacitance for easy paralleling
- Hermetically sealed surface mount package
- Low inductance package
- TX, TXV and Space Level screening available

**MILPACK**

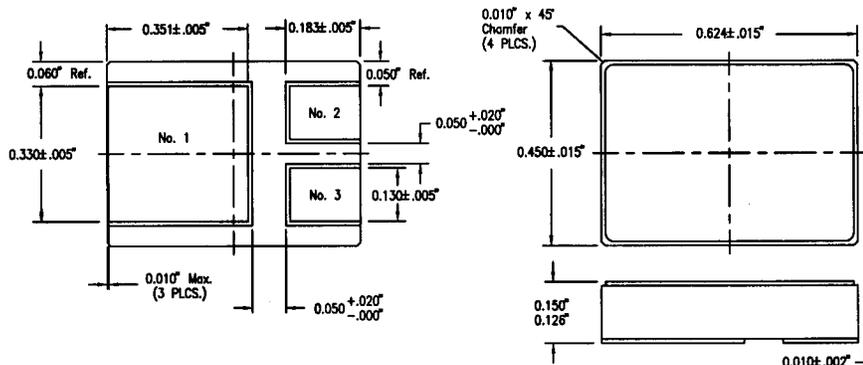


**MAXIMUM RATINGS**

CHARACTERISTIC	SYMBOL	VALUE	UNIT
Drain to Source Voltage	V <sub>DS</sub>	600	Volts
Gate to Source Voltage	V <sub>GS</sub>	±20	Volts
Continuous Drain Current @TC=25°C @TC=100°C	I <sub>D</sub>	11 7	Amps
Operating and Storage Temperature	T <sub>op</sub> & T <sub>stg</sub>	-55 to +150	°C
Thermal Resistance, Junction to Case	R <sub>θJC</sub>	1.25	°C/W
Total Device Dissipation @ TC=25°C Total Device Dissipation @ TC=55°C	P <sub>D</sub>	100 76	Watts
Single Pulse Avalanche Energy	E <sub>AS</sub>	920	mJ
Repetitive Avalanche Energy	E <sub>AR</sub>	18	mJ

**PACKAGE OUTLINE: MILPACK**

**PIN OUT:**  
 PIN 1: DRAIN  
 PIN 2: SOURCE  
 PIN 3: GATE



**NOTE: All specifications are subject to change without notification. SCD's for these devices should be reviewed by SSDI prior to release.**

**DATA SHEET #: F00297 A**

**MED**

**SFFC50**

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**ELECTRICAL CHARACTERISTICS @ T<sub>J</sub>=25°C (Unless Otherwise Specified)**

RATING		SYMBOL	MIN	TYP	MAX	UNIT
Drain to Source Breakdown Voltage (V <sub>GS</sub> =0 V, I <sub>D</sub> =250μA)		BV <sub>DSS</sub>	600	---	---	V
Temperature Coefficient of Breakdown Voltage		$\frac{\Delta BV_{DSS}}{\Delta T_j}$	---	780	---	mV/°C
Drain to Source on State Resistance (V <sub>GS</sub> =10 V)	I <sub>D</sub> =6 A I <sub>D</sub> =11 A	R <sub>DS(on)</sub>		0.5 0.5	0.60 0.65	Ω
Gate Threshold Voltage (V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA)		V <sub>GS(th)</sub>	2		4	V
Forward Transconductance (V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =6 A)		g <sub>fs</sub>	5.7	13	--	S(Ω)
Zero Gate Voltage Drain Current (V <sub>DS</sub> =80% rated voltage, V <sub>GS</sub> =0 V) (V <sub>DS</sub> =80% rated V <sub>DS</sub> , V <sub>GS</sub> =0 V, T <sub>A</sub> =125°C)		I <sub>DSS</sub>	---	---	100 500	μA
Gate to Source Leakage Forward Gate to Source Leakage Reverse	At rated V <sub>GS</sub>	I <sub>GSS</sub>	---	---	100 -100	nA
Total Gate Charge Gate to Source Charge Gate to Drain Charge	V <sub>GS</sub> =10 Volts V <sub>DS</sub> =360 V Rated I <sub>D</sub>	Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	---	100 11 56	140 20 69	nC
Turn on Delay Time Rise Time Turn Off Delay Time Fall Time	V <sub>DD</sub> =50% rated V <sub>DS</sub> rated I <sub>D</sub> R <sub>G</sub> =6.2Ω	t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub>	---	21 10 65 18	30 20 100 25	nsec
Diode Forward Voltage (I <sub>S</sub> =rated I <sub>D</sub> , V <sub>GS</sub> =0 V, T <sub>J</sub> =25°C)		V <sub>SD</sub>	---	---	1.4	V
Diode Reverse Recovery Time Reverse Recovery Charge	T <sub>J</sub> =25°C I <sub>F</sub> =rated I <sub>D</sub> di/dt=100 A/μsec	t <sub>rr</sub> Q <sub>RR</sub>	---	450 3.9	830 ---	nsec μC
Input Capacitance Output Capacitance Reverse Transfer Capacitance	V <sub>GS</sub> =0 Volts V <sub>DS</sub> =25 Volts f= 1 MHz	C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	---	2500 350 55	---	pF